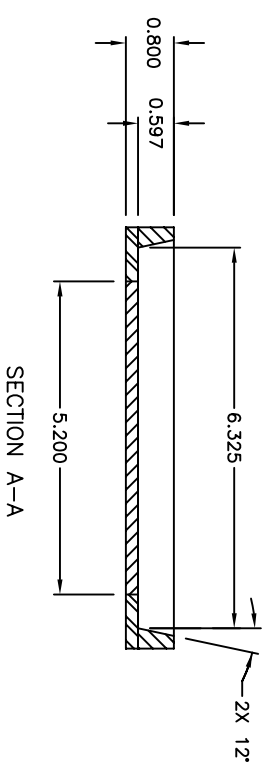
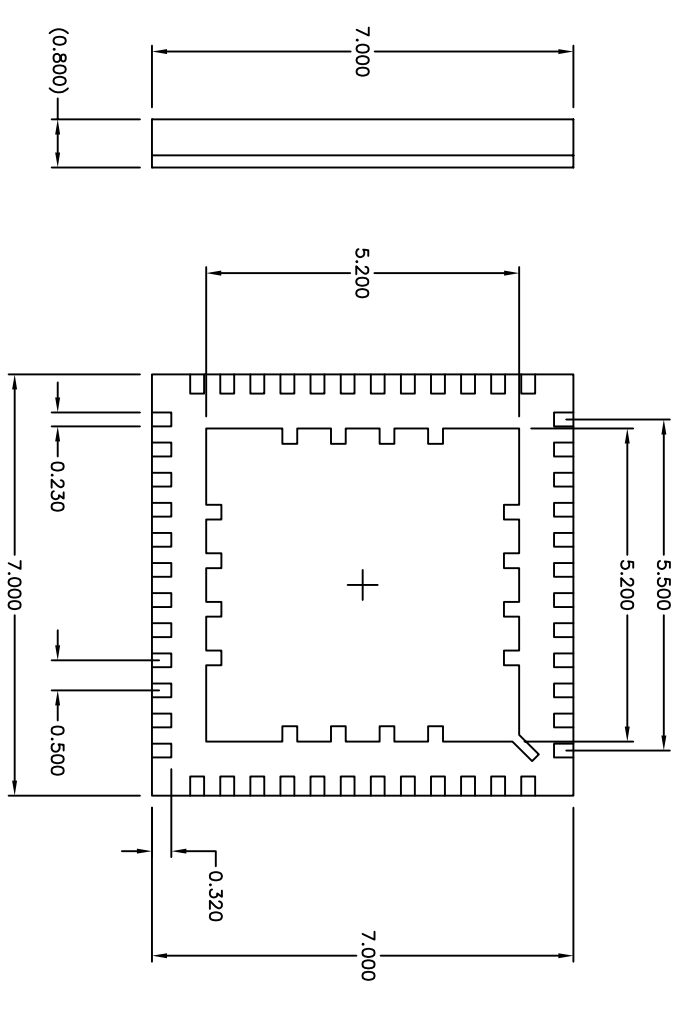
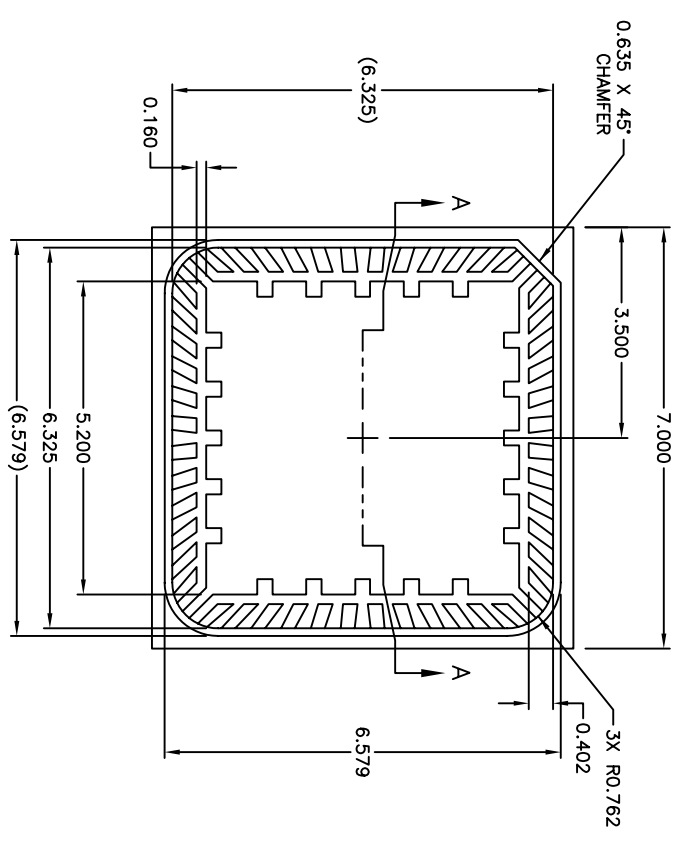


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REVISIONS			APPROVED
ECN NO.	DATE	DESCRIPTION	
10501	10/27/05	PRODUCTION RELEASE	D.BENANDIO



- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
  2. LEAD FRAME: COPPER, FH 194.
  3. LEAD FINISH: FULL GOLD PLATE.
  4. FRAME THICKNESS: 0.2030 ±.0076.
  5. DIE PAD: 5.200 X 5.200.
  6. JEDEC OUTLINE: MO-220 (YKKD).



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS  
 TOLERANCES ARE: X.XXX ± 0.15 X.XXXX ± 0.0100 ANGLES: ± 1°  
 DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	10/26/05
APP BY	P. FLASKERUD	DATE	10/26/05
CUSTOMER	----		

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 PHONE: (408) 400-9002 FAX: (408) 400-9006

48 Lead 7mm x 7mm  
 MLP Open-Pak

SIZE	PART NO.	REV
A	MLP7X7-48-OP-02	2
SCALE	NONE	
CAD FILE	MLP7X7-48-OP-02-R2.DWG	
SHEET	1 OF 1	

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